### MAX3223 3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER

SLLS409D - JANUARY 2000 - REVISED AUGUST 2002

- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V V<sub>CC</sub> Supply
- Operates up to 250 kbit/s
- Two Drivers and Two Receivers
- Low Standby Current . . . 1 μA Typical
- External Capacitors . . . 4 × 0.1 μF
- Accepts 5-V Logic Input With 3.3-V Supply
- Designed to Be Interchangeable With Maxim MAX3223
- RS-232 Bus-Pin ESD Protection Exceeds ±15 kV Using Human-Body Model (HBM)
- Applications
  - Battery-Powered Systems, PDAs,
    Notebooks, Laptops, Palmtop PCs, and
    Hand-Held Equipment

#### DB, DW, OR PW PACKAGE (TOP VIEW) 20 FORCEOFF EN C1+ [] 2 19 VCC V+[]3 18 GND 17 DOUT1 C1- $\Pi_4$ C2+ [] 5 16 RIN1 C2-[] 6 15 ROUT1 V−**П** 7 14 | FORCEON DOUT2 8 13 DIN1 RIN2 9 12 ¶ DIN2 ROUT2 10 11 NVALID

## description/ordering information

The MAX3223 consists of two line drivers, two line receivers, and a dual charge-pump circuit with  $\pm 15$ -kV ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. The device operates at data signaling rates up to 250 kbit/s and a maximum of 30-V/ $\mu$ s driver output slew rate.

### **ORDERING INFORMATION**

TA	PACKAGE	<u>:</u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SOIC (DW)	Tube	MAX3223CDW	MAX3223C
−0°C to 70°C	SOIC (DW)	Tape and reel	MAX3223CDWR	WAX3223C
-0 0 10 70 0	SSOP (DB)	Tape and reel	MAX3223CDBR	MA3223C
	TSSOP (PW)	Tape and reel	MAX3223CPWR	MA3223C
	SOIC (DW)	Tube	MAX3223IDW	MAX3223I
-40°C to 85°C	SOIC (DW)	Tape and reel	MAX3223IDWR	IVIAA3223I
-40 C to 65 C	SSOP (DB)	Tape and reel	MAX3223IDBR	MB3223I
	TSSOP (PW)	Tape and reel	MAX3223IPWR	MB3223I

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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### description/ordering information (continued)

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and  $\overline{\text{FORCEOFF}}$  is high. During this mode of operation, if the device does not sense a valid RS-232 signal, the driver outputs are disabled. If  $\overline{\text{FORCEOFF}}$  is set low and  $\overline{\text{EN}}$  is high, both drivers and receivers are shut off, and the supply current is reduced to 1  $\mu$ A. Disconnecting the serial port or turning off the peripheral drivers causes auto-powerdown to occur. Auto-powerdown can be disabled when FORCEON and  $\overline{\text{FORCEOFF}}$  are high. With auto-powerdown enabled, the device is activated automatically when a valid signal is applied to any receiver input. The  $\overline{\text{INVALID}}$  output is used to notify the user if an RS-232 signal is present at any receiver input.  $\overline{\text{INVALID}}$  is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V or has been between -0.3 V and 0.3 V for less than 30  $\mu$ s.  $\overline{\text{INVALID}}$  is low (invalid data) if the receiver input voltage is between -0.3 V and 0.3 V for more than 30  $\mu$ s. Refer to Figure 4 for receiver input levels.

#### **Function Tables**

#### **EACH DRIVER**

		INPUTS		OUTPUT	
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL	DOUT	DRIVER STATUS
Х	Χ	L	Х	Z	Powered off
L	Н	Н	Х	Н	Normal operation with
Н	Н	Н	Х	L	auto-powerdown disabled
L	L	Н	Yes	Н	Normal operation with
Н	L	Н	Yes	L	auto-powerdown enabled
L	L	Н	No	Z	Powered off by
Н	L	Н	No	Z	auto-powerdown feature

H = high level, L = low level, X = irrelevant, Z = high impedance

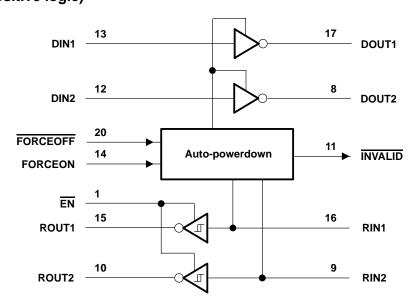
#### **EACH RECEIVER**

	INP	PUTS	OUTPUT
RIN	EN	VALID RIN RS-232 LEVEL	ROUT
L	L	Х	Н
Н	L	Х	L
Х	Н	Х	Z
Open	L	No	Н

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off



## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub> (see Note 1)	
Positive output supply voltage range, V+ (see Note 1)	
Negative output supply voltage range, V- (see Note 1)	0.3 V to –7 V
Supply voltage difference, V+ – V– (see Note 1)	13 V
Input voltage range, V <sub>I</sub> : Driver, FORCEOFF, FORCEON, EN	–0.3 V to 6 V
Receiver	
Output voltage range, VO: Driver	–13.2 V to 13.2 V
Receiver, INVALID	0.3 V to V <sub>CC</sub> + 0.3 V
Package thermal impedance, $\theta_{JA}$ (see Note 2): DB package	
DW package	58°C/W
PW package	83°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T <sub>Stq</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



NOTES: 1. All voltages are with respect to network GND.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 3 and Figure 6)

						MAX	UNIT
	Supply voltage		V <sub>CC</sub> = 3.3 V	3	3.3	3.6	٧
			V <sub>CC</sub> = 5 V	4.5	5	5.5	V
V	Driver and control high-level input voltage	DIN, EN, FORCEOFF,	$V_{CC} = 3.3 \text{ V}$	2			٧
VIH	Driver and control night-level input voltage	FORCEON	V <sub>CC</sub> = 5 V	2.4			V
$V_{IL}$	Driver and control low-level input voltage	DIN, EN, FORCEOFF, FORCEO	N			0.8	V
٧,	Driver and control input voltage	DIN, EN, FORCEOFF, FORCEO	N	0		5.5	V
٧ı	Receiver input voltage			-25		25	V
т.	T <sub>A</sub> Operating free-air temperature		MAX3223C	0	•	70	°C
'A			MAX3223I	-40		85	C

NOTE 3: Test conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

### electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

PARAMETER		TEST CONDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT	
II	Input leakage current	EN, FORCEOFF, FORCEON			±0.01	±1	μΑ
		Auto-powerdown disabled	No load, FORCEOFF, FORCEON at V <sub>CC</sub>		0.3	1	mA
Icc	Supply current	Powered off	No load, FORCEOFF at GND		1	10	
	сарру санон	Auto-powerdown enabled	No load, FORCEOFF at V <sub>CC</sub> , FORCEON at GND, All RIN are open or grounded		1	10	μΑ

† All typical values are at  $V_{CC}$  = 3.3 V or  $V_{CC}$  = 5 V, and  $T_A$  = 25°C. NOTE 3: Test conditions are C1–C4 = 0.1  $\mu$ F at  $V_{CC}$  = 3.3 V  $\pm$  0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at  $V_{CC}$  = 5 V  $\pm$  0.5 V.



### **DRIVER SECTION**

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

	PARAMETER	TEST CONDITIONS		MIN	TYP <sup>†</sup>	MAX	UNIT	
Vон	High-level output voltage	DOUT at $R_L = 3 \text{ k}\Omega$ to GN	D		5	5.4		V
VOL	Low-level output voltage	DOUT at $R_L = 3 \text{ k}\Omega$ to GN	DOUT at R <sub>L</sub> = $3 \text{ k}\Omega$ to GND		<b>-</b> 5	-5.4		V
lн	High-level input current	$V_I = V_{CC}$				±0.01	±1	μΑ
IJL	Low-level input current	V <sub>I</sub> at GND				±0.01	±1	μΑ
loo	Oh	V <sub>CC</sub> = 3.6 V,	VO = 0 V			±35	±60	mA
los	Short-circuit output current <sup>‡</sup>	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0 V			±35	±60	ША
ro	Output resistance	$V_{CC}$ , V+, and V- = 0 V,	$V_0 = \pm 2 V$		300	10M	·	Ω
l <sub>off</sub>	Output leakage current	FORCEOFF = GND,	$V_0 = \pm 12 V$ ,	$V_{CC} = 0 \text{ to } 5.5 \text{ V}$			±25	μΑ

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .

NOTE 3: Test conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V ± 0.5 V.

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

	PARAMETER	TEST CON	TEST CONDITIONS			MAX	UNIT
	Maximum data rate	C <sub>L</sub> = 1000 pF, One DOUT switching,	$R_L = 3 k\Omega$ , See Figure 1	150	250		kbit/s
tsk(p)	Pulse skew§	C <sub>L</sub> = 150 pF to 2500 pF, See Figure 2	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega,$		100		ns
SR(tr)	Slew rate, transition region	V <sub>CC</sub> = 3.3 V,	C <sub>L</sub> = 150 pF to 1000 pF	6		30	\//uo
J SK(II)	(See Figure 1)	$R_L = 3 k\Omega$ to $7 k\Omega$	C <sub>L</sub> = 150 pF to 2500 pF	4		30	V/μs

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .

NOTE 3: Test conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.



<sup>\$</sup> Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

<sup>§</sup> Pulse skew is defined as |tplH - tpHL| of each channel of the same device.

### RECEIVER SECTION

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Vон	High-level output voltage	I <sub>OH</sub> = -1 mA	V <sub>CC</sub> -0.6	V <sub>CC</sub> -0.1		V
VOL	Low-level output voltage	I <sub>OL</sub> = 1.6 mA			0.4	V
\/	Positive-going input threshold voltage	V <sub>CC</sub> = 3.3 V		1.6	2.4	V
VIT+	Fositive-going input tilleshold voltage	V <sub>CC</sub> = 5 V		1.9	2.4	V
\/	Negative-going input threshold voltage	V <sub>CC</sub> = 3.3 V	0.6	1.1		V
VIT-	Negative-going input tilleshold voltage	V <sub>CC</sub> = 5 V	0.8	1.4		V
V <sub>hys</sub>	Input hysteresis (V <sub>IT+</sub> - V <sub>IT-</sub> )			0.5		V
l <sub>off</sub>	Output leakage current	EN = V <sub>CC</sub>		±0.05	±10	μΑ
rį	Input resistance	$V_I = \pm 3 \text{ V to } \pm 25 \text{ V}$	3	5	7	kΩ

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .

NOTE 3: Test conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3)

	PARAMETER	PARAMETER TEST CONDITIONS		MIN TYP†	MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	C <sub>L</sub> = 150 pF,	See Figure 3	150		ns
tPHL	Propagation delay time, high- to low-level output	C <sub>L</sub> = 150 pF,	See Figure 3	150		ns
t <sub>en</sub>	Output enable time	C <sub>L</sub> = 150 pF, See Figure 4	$R_L = 3 k\Omega$ ,	200		ns
t <sub>dis</sub>	Output disable time	C <sub>L</sub> = 150 pF, See Figure 4	$R_L = 3 k\Omega$ ,	200		ns
t <sub>sk(p)</sub>	Pulse skew <sup>‡</sup>	See Figure 3		50		ns

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .

NOTE 3: Test conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.



<sup>‡</sup> Pulse skew is defined as |tpLH - tpHL| of each channel of the same device.

### **AUTO-POWERDOWN SECTION**

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

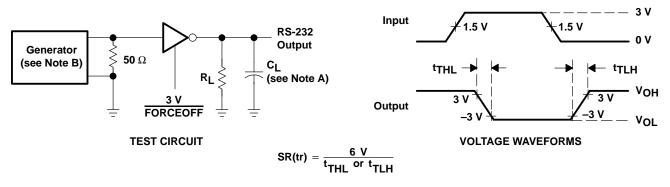
	PARAMETER	TEST C	ONDITIONS	MIN	MAX	UNIT
V <sub>T+(valid)</sub>	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND,	FORCEOFF = V <sub>CC</sub>		2.7	٧
V <sub>T</sub> –(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND,	FORCEOFF = V <sub>CC</sub>	-2.7		V
VT(invalid)	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND,	FORCEOFF = V <sub>CC</sub>	-0.3	0.3	V
VOH	INVALID high-level output voltage	$\frac{I_{OH} = -1 \text{ mA},}{FORCEOFF} = V_{CC}$	FORCEON = GND,	V <sub>CC</sub> -0.6	·	V
VOL	INVALID low-level output voltage	I <sub>OL</sub> = 1.6 mA, FORCEOFF = V <sub>CC</sub>	FORCEON = GND,		0.4	V

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TYP	UNIT
<sup>t</sup> valid	Propagation delay time, low- to high-level output	1	μs
<sup>t</sup> invalid	Propagation delay time, high- to low-level output	30	μs
t <sub>en</sub>	Supply enable time	100	μs

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .

#### PARAMETER MEASUREMENT INFORMATION

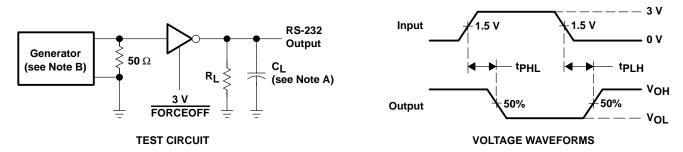


NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_f \le 10$  ns.

Figure 1. Driver Slew Rate

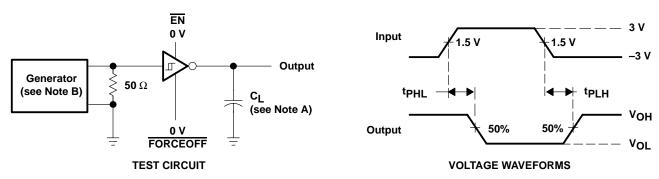
### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \le 10$  ns.  $t_f \le 10$  ns.

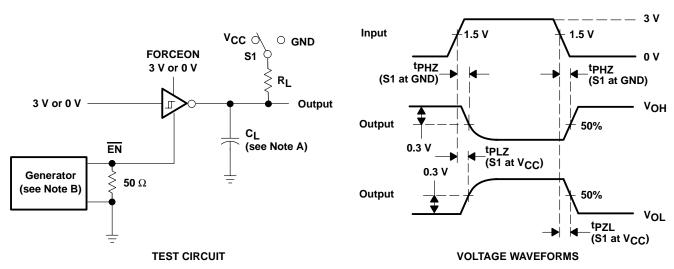
Figure 2. Driver Pulse Skew



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The pulse generator has the following characteristics:  $Z_O$  = 50  $\Omega$ , 50% duty cycle,  $t_f \le$  10 ns,  $t_f \le$  10 ns.

Figure 3. Receiver Propagation Delay Times



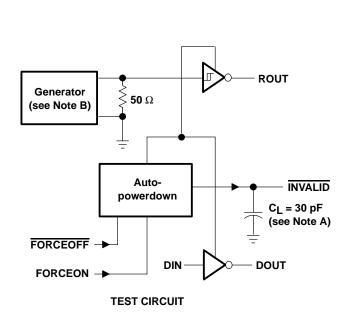
NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

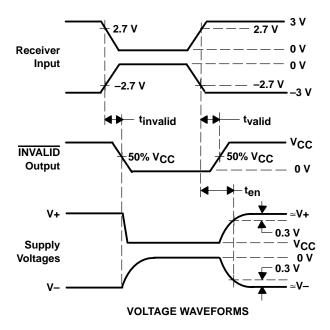
B. The pulse generator has the following characteristics:  $Z_O = 50 \ \Omega$ , 50% duty cycle,  $t_f \le 10 \ ns$ ,  $t_f \le 10 \ ns$ .

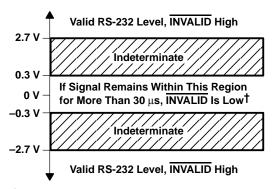
Figure 4. Receiver Enable and Disable Times



### PARAMETER MEASUREMENT INFORMATION







 $\mbox{\dag}$  Auto-powerdown disables drivers and reduces supply current to 1  $\mu A.$ 

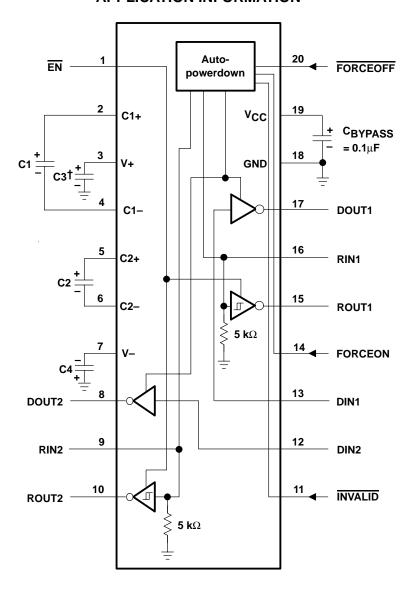
NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 5 kbit/s,  $Z_O$  = 50  $\Omega$ , 50% duty cycle,  $t_f \le 10$  ns,  $t_f \le 10$  ns.

Figure 5. INVALID Propagation Delay Times and Supply Enabling Time



### **APPLICATION INFORMATION**



 $^\dagger$  C3 can be connected to VCC or GND. NOTE A: Resistor values shown are nominal.

### **V<sub>CC</sub>** vs CAPACITOR VALUES

v <sub>CC</sub>	C1	C2, C3, C4
$\begin{array}{c} \textbf{3.3 V} \pm \textbf{0.3 V} \\ \textbf{5 V} \pm \textbf{0.5 V} \\ \textbf{3 V to 5.5 V} \end{array}$	0.1 μF 0.047 μF 0.1 μF	0.1 μF 0.33 μF 0.47 μF

Figure 6. Typical Operating Circuit and Capacitor Values



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